



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application

Inventor(s): Nguyen

Appln. No.: 10/795,950

Confirm. No.: 1419

Filed: March 8, 2004

Title: Multilayer Copper Structure for Improving  
Adhesion Property

PATENT APPLICATION

Art Unit: 2823

Examiner: Jarrett J. Stark

**Customer No. 23910**

**CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.8**

I hereby certify that this correspondence is being deposited in the United States Postal Service with sufficient postage as first class mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on February 15, 2006.

*Susan Boucher* (Signature)

Susan Boucher

Signature Date: February 15, 2006

**REPLY TO OFFICE ACTION UNDER 37 C.F.R. § 1.111**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Office Communication of December 13, 2005, please amend the above-identified application as follows:

**Remarks/Arguments** begin on page 2 of this paper.